

**AMENDMENTS TO THE CLAIMS**

**This listing of claims will replace all prior versions and listings of claims in the application:**

**LISTING OF CLAIMS:**

1. (previously presented) A water-permeable adhesive tape for processing semiconductor wafers and/or semiconductor related materials, comprising at least one base film which possesses perforations and has a cavity ratio of 3.0 to 90%; and an adhesive not having perforations applied on one surface of the base film.
2. (original) The water-permeable adhesive tape according to claim 1, wherein the base film comprises a synthetic resin or a non-woven fabric.
3. (original) The water-permeable adhesive tape according to claim 1 or 2, wherein the size of the perforations is from 0.001 to 3.0 mm<sup>2</sup>.
4. (previously presented) The water-permeable adhesive tape according to any of claims 1 or 2, wherein the adhesive comprises a rubber-based or acrylic-based adhesive.
5. (previously presented) The water-permeable adhesive tape according to any of claims 1 or 2, wherein the adhesive is pressure-sensitive, light-sensitive and/or heat-sensitive.
6. (previously presented) The water-permeable adhesive tape according to any of claims 1 or 2, having an elongation of more than 10%.
7. (previously presented) The water-permeable adhesive tape according to any of claims 1 or 2, having a tensile strength of more than 0.1 N/20 mm.
8. (previously presented) The water-permeable adhesive tape according to any of claims 1 or 2, having an adhesive strength of 0.15 to 10 N/20 mm.
9. (currently amended): A method of processing semiconductor wafers and/or semiconductor-related materials, comprising a step of fixing a semiconductor wafer or

AMENDMENT

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semiconductor material with the water-permeable adhesive tape according to Claim 1 prior to processing the wafer or material.